

TRASKBRITT

Intellectual Property Attorneys

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Ed Kirchmeier
Micron Technology, Inc.
Mailstop 525
8000 South Federal Way
Boise, ID 83707-0006

Re: U.S. PATENT APPLICATION

Invention	LEADLESS PACKAGING FOR IMAGE SENSOR DEVICES AND METHODS OF ASSEMBLY
Inventor	Boon et al.
Assignee	Micron Technology, Inc.
Application No.	10/693,376
Filing Date	October 23, 2003
Your Ref No.	02-0240.01/US
Our Case No.	2269-5353.1US

Dear Ed:

Enclosed is a copy of a Supplemental Information Disclosure Statement for the U.S. Patent application identified above which was filed today in the U.S. Patent and Trademark Office. We will notify you of further actions issued by the Patent Office as we receive them.

If you have any questions, please do not hesitate to contact me.

Very truly yours,

Shawnee L. MacDonald
Legal Staff Assistant

KLD/dp:slm

Document in ProLaw

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THE PATENT & TRADEMARK OFFICE MAILROOM DATE
STAMPED HEREON IS AN ACKNOWLEDGEMENT THAT ON THIS
DATE THE PATENT & TRADEMARK OFFICE RECEIVED

Supplemental Information Disclosure Statement (2 pages),
Form PTO/SB/08A (1 page).

Invention: LEADLESS PACKAGING FOR IMAGE SENSOR
DEVICES AND METHODS OF ASSEMBLY
Applicant(s): Boon et al.
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Serial No.: 10/693,376
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